

**Milplex Circuits, Inc.**  
 1301 W. Ardmore Avenue  
 Itasca, IL 60143-1104  
 630 250-1580  
 Fax 250-1590

[Sales@milplex.com](mailto:Sales@milplex.com)  
[www.milplex.com](http://www.milplex.com)

Manufacturing Capabilities – UL Approved 94V0  
 ISO 9001:2008 Registered

| <b>Item</b>                        |                           | <b>Capability</b>                                 |                             |
|------------------------------------|---------------------------|---------------------------------------------------|-----------------------------|
| Laminate Material                  | FR-4                      | 0.020" Min. 0.125" Max.                           |                             |
| Laminate Material                  | High Tg                   | Tg = 170 and others                               |                             |
| Copper Thickness                   |                           | 1/2 oz. minimum start                             |                             |
|                                    |                           | 2 oz. max start – 4 oz.<br>max. finished          |                             |
| Layer Count                        |                           | Up to 10 layers                                   |                             |
| Hole size (drilled)                |                           | 0.010" Min. Plated,<br>0.250 Max.                 |                             |
| Land size<br>(Diameter over drill) |                           | 0.010" Min.<br>Outer Layers                       | 0.035" Min.<br>Inner Layers |
| Trace / Space                      |                           | 0.004" Outer Layers                               |                             |
| Trace / Space                      |                           | 0.005" Inner Layers                               |                             |
| Copper Plating                     | Aspect Ratio              | 6 : 1                                             |                             |
| Copper Plating                     |                           | Min. 0.007" through<br>holes                      |                             |
| Solder Mask                        | Thickness                 | 0.004" Min. 0.008" Max                            |                             |
|                                    | Dam Width                 | 0.004" Min.                                       |                             |
|                                    | Registration              | +/- 0.002"                                        |                             |
| Profiling                          | Routing                   | 0.030" Min. Width                                 |                             |
|                                    | Scoring                   | Copper min. 0.015"<br>from score line             |                             |
| Impedance Control                  | Based on trace<br>width   | Tolerance 10%                                     |                             |
| Silkscreen                         | For Legible<br>Characters | Min. Text Height 0.070"<br>Min. Text Width 0.008" |                             |
|                                    |                           | Min. Text Spacing<br>0.008"                       |                             |
| Surface Coatings                   |                           | Solder HASL                                       |                             |
|                                    |                           | Lead Free Solder HASL                             |                             |
|                                    |                           | Entek                                             |                             |
|                                    |                           | Immersion Tin                                     |                             |
|                                    |                           | Immersion Silver                                  |                             |
|                                    |                           | Immersion Ni/Au                                   |                             |